

## Description

The HSM4002 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

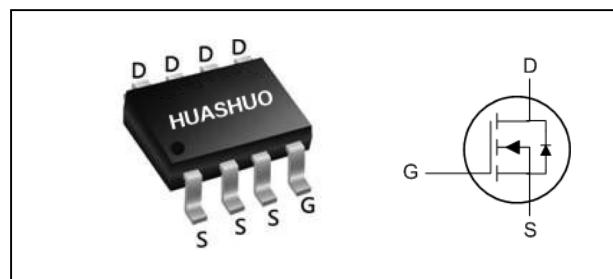
The HSM4002 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

$V_{DS}$	40	V
$R_{DS(ON),max}$	28	mΩ
$I_D$	7.5	A

## SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	7.5	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	30	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	12	mJ
$I_{AS}$	Avalanche Current	15	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	50	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

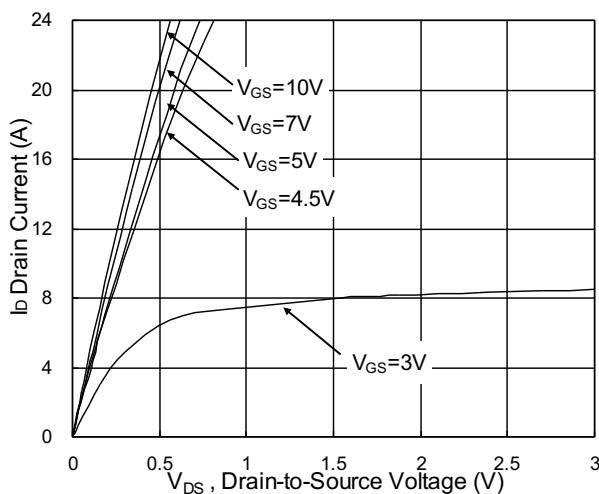
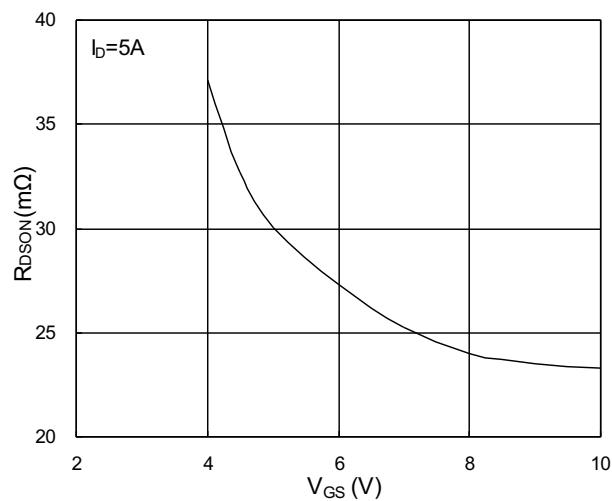
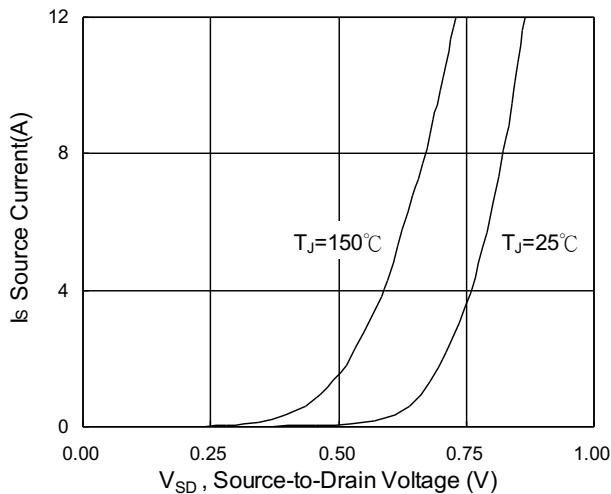
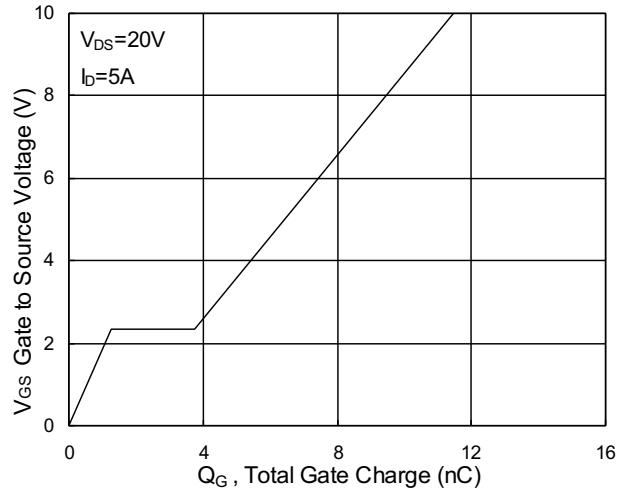
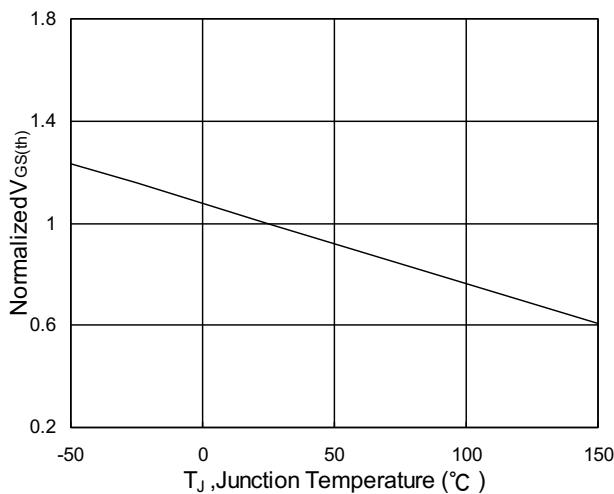
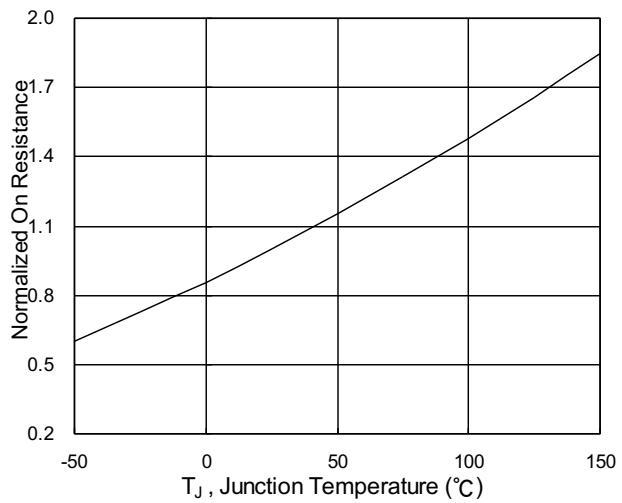
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=5\text{A}$	---	---	28	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	---	38	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.56	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=5\text{A}$	---	14	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.6	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	5.5	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	1.25	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.5	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=20\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=1\text{A}$	---	8.9	---	$\text{ns}$
$T_r$	Rise Time		---	2.2	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	41	---	
$T_f$	Fall Time		---	2.7	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	593	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	76	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	56	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	7.5	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	30	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=15\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs. G-S Voltage**

**Fig.3 Forward Characteristics of Reverse**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**

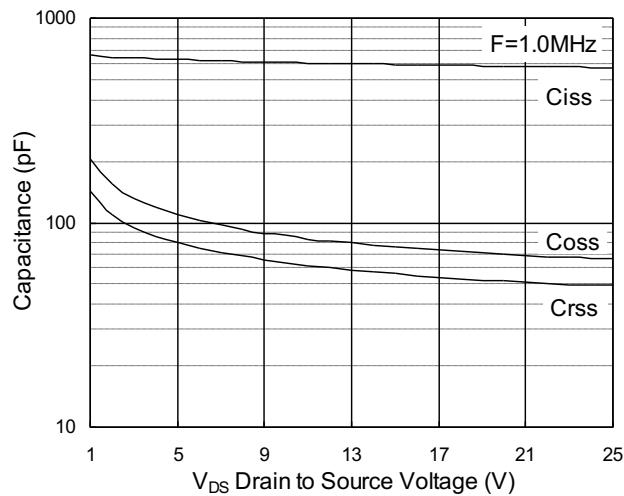


Fig.7 Capacitance

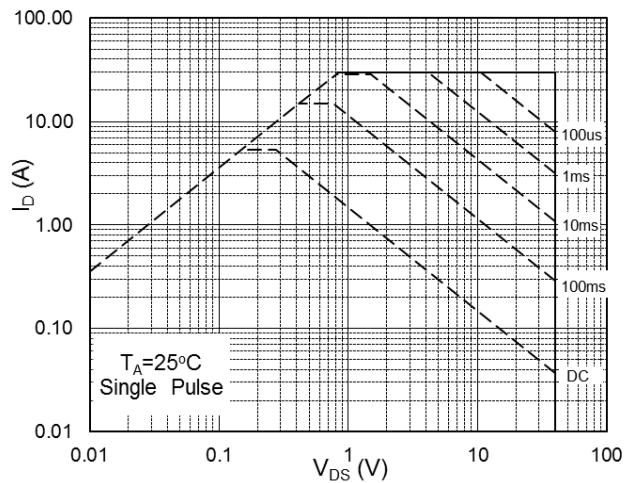


Fig.8 Safe Operating Area

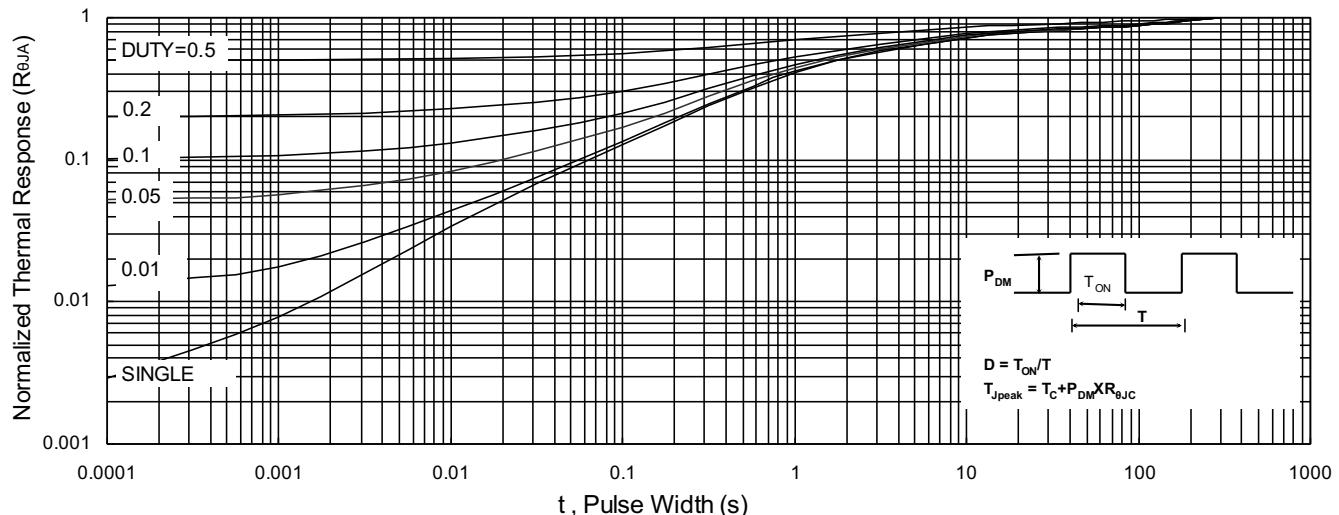


Fig.9 Normalized Maximum Transient Thermal Impedance

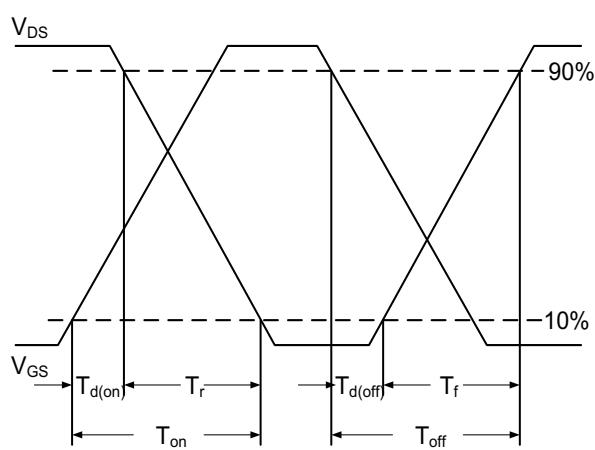


Fig.10 Switching Time Waveform

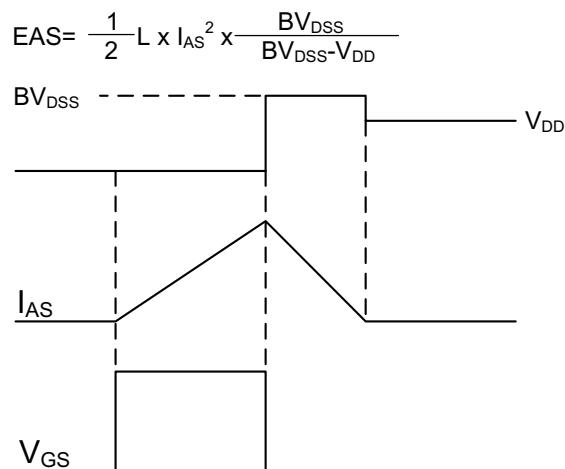


Fig.11 Unclamped Inductive Switching Waveform

## Ordering Information

Part Number	Package code	Packaging
HSM4002	SOP-8	2500/Tape&Reel

